L Number	Hits	Search Text	DB	Time stamp
1	4277	(438/$.ccls.) and (bond$3 solder$3) same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)	USPAT	2004/07/19 16:17
2	1747	((438/$.ccls.) and (bond$3 solder$3) same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and bond$3 same solder$3 same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)	USPAT	2004/07/19 16:18
3	0	(((438/$.ccls.) and (bond$3 solder$3) same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and bond$3 same solder$3 same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and solder$3 near7 (IC chip$1 die$1 dice) same "or" same solder$3 near7 (substrate$1 carrier board pcb)	USPAT	2004/07/19 16:20
4	1155	(((438/$.ccls.) and (bond$3 solder$3) same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and bond$3 same solder$3 same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and solder$3 near7 (IC chip$1 die$1 dice device$1) same solder$3 near7 (substrate$1 carrier board pcb)	USPAT	2004/07/19 16:22
5	947	((((438/$.ccls.) and (bond$3 solder$3) same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and bond$3 same solder$3 same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and solder$3 near7 (IC chip$1 die$1 dice device$1) same solder$3 near7 (substrate$1 carrier board pcb)) and (bond$3 weld$3 join$3) near10 (IC chip$1 die$1 dice device$1) near3 (substrate$1 carrier board pcb)	USPAT	2004/07/19 16:26
6	159	(((((438/$.ccls.) and (bond$3 solder$3) same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and bond$3 same solder$3 same (IC chip$1 die$1 dice) near15 (substrate$1 carrier board pcb)) and solder$3 near7 (IC chip$1 die$1 dice device$1) same solder$3 near7 (substrate$1 carrier board pcb)) and (bond$3 weld$3 join$3) near10 (IC chip$1 die$1 dice device$1) near3 (substrate$1 carrier board pcb)) and (deposit$4 application appli$2 applying) near3 (solder$3 braz$3) near10 (IC chip$1 die$1 dice device$1) and (deposit$4 application appli$2 applying) near3 (substrate$1 carrier board pcb)	USPAT	2004/07/19 16:29